Heatsink Extruded

multicomp

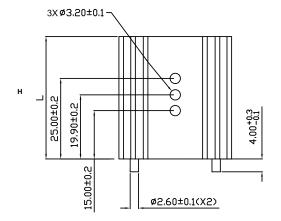


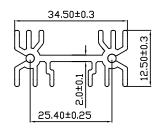
Description:

Compact, vertical mounting extruded heatsink with solderable fixing pins. Predrilled for a single TO-220 package or via clip available separately.

Features:

- Choice of thermal resistance
- Solderable mounting pins
- · Pre-drilled mounting holes
- Black anodize finish





Dimensions : Millimetres

Part Number	Thermal Resistance	Height	Height
MC33288	11.4°C/W	25	
MC33289	10.2°C/W	38	34.53
MC33290	8.8°C/W	50	

Dimensions : Millimetres

Part Number Table

Description	Part Number
Heatsink TO-220 11.4°C/W 3 Holes	MC33288
Heatsink TO-220 10.2°C/W 3 Holes	MC33289
Heatsink TO-220 8.8°C/W 3 Holes	MC33290

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